AMENDMENTS TO THE CLAIMS:

Claims 1-14 (cancelled)

15. (Currently Amended) A circuit substrate to be used for packaging a semiconductor device, comprising:

a main body having input/output terminal electrodes on a surface thereof, with each of said input/output terminal electrodes having

(i) a first surface that opposes said surface of said main body, and

(ii) a second surface that faces in a direction opposite to that in which said first surface faces; and

a resin film having conductive adhesive portions, composed of conductive adhesive including thermoplastic resins or thermosetting resins, on a surface of said resin film, each of said conductive adhesive portions having

(i) a first surface that opposes said surface of said resin film, and

(ii) a second surface that faces in a direction opposite to that in which said first surface faces,

wherein the circuit substrate is formed by bonding said resin film onto said main body such that said conductive adhesive portions are positioned on said input/output terminal electrodes, respectively, and said resin film covers said surface of said main body and said input/output terminal electrodes along with said conductive adhesive portions.

~~conductive adhesive portions on said input/output terminal electrodes, with each of said conductive adhesive portions having~~

~~(i) a first surface that opposes said second surface of a respective one of said input/output terminal electrodes, and~~

~~(ii) a second surface that faces in a direction opposite to that in which said first surface faces; and~~

~~a resin film on said surface of said main body and covering said input/output terminal electrodes along with said conductive adhesive portions such that said resin film covers said first and~~

~~second surfaces of said input/output terminal electrodes and also covers said first and second surfaces of said conductive adhesive portions.~~

16. (Previously presented) The circuit substrate according to claim 15, wherein said resin film contacts said second surface of said conductive adhesive portions.

17. (Previously presented) The circuit substrate according to claim 16, wherein said resin film contacts said second surface of said input/output terminal electrodes.

18. (Previously presented) The circuit substrate according to claim 15, wherein

each of said input/output terminal electrodes has a top side, a bottom side, and a lateral side interconnecting said top and bottom sides,

each of said conductive adhesive portions has a top side, a bottom side, and a lateral side interconnecting said top and bottom sides,

said resin film completely covers each of said input/output terminal electrodes on two of said top side, said bottom side and said lateral side thereof, and

said resin film completely covers each of said conductive adhesive portions on two of said top side, said bottom side and said lateral side thereof.

19. (Currently Amended) A circuit substrate to have mounted thereon a semiconductor device, comprising:

a main body having input/output terminal electrodes on a surface thereof; and

a resin film having on one surface thereof conductive adhesive portions, and having on an opposite surface thereof an elastomer layer, said resin film being initially separate from said main body, said conductive adhesive portions being composed of conductive adhesive including thermoplastic resins or thermosetting resins,

wherein on the circuit substrate, a semiconductor device is to be mounted by

(i) superposing said resin film and said main body such that said conductive adhesive portions are positioned on corresponding ones of said input/output terminal electrodes, and

(ii) pressing bump electrodes of the semiconductor device into said resin film so as to reach said conductive adhesive portions and be connected to said corresponding ones of said input/output terminal electrodes,

wherein said elastomer layer is positioned on said opposite surface so as to correspond with at least part of a surface of ~~a~~ the semiconductor device on which a functional part of the semiconductor device resides, when the semiconductor device is mounted on the circuit substrate; ~~and~~

~~wherein said conductive adhesive portions are positioned on said one surface so as to correspond with said input/output terminal electrodes~~.

20. (Currently Amended) The circuit substrate according to claim 19, wherein said resin film~~, with said conductive adhesive portions on said one surface thereof and with said elastomer layer on said opposite surface thereof, is initially separate from said main body and is then~~ becomes attached to said main body during the pressing of the bump electrodes of the semiconductor device into said resin film.

21. (Previously presented) The circuit substrate according to claim 20, wherein said elastomer layer is softer and more elastic than said resin film.

22. (Previously presented) The circuit substrate according to claim 19, wherein said elastomer layer is softer and more elastic than said resin film.

23. (Currently Amended) A package structure comprising:

a circuit substrate having input/output terminal electrodes, and conductive adhesive, including thermoplastic resins or thermosetting resins, on each of said input/output terminal electrodes;

a semiconductor device having bump electrodes that are electrically and mechanically connected to said conductive adhesive and to said input/output terminal electrodes, said bump electrodes being in contact with said input/output terminal electrodes; and

a resin layer between said circuit substrate and said semiconductor device, said resin layer bonding and fixing said semiconductor device to said circuit substrate,

wherein the package structure is formed by

(i) superposing a resin film, having said conductive adhesive portions, and a main body, having said input/output terminal electrodes, such that said conductive adhesive portions are positioned on corresponding ones of said input/output terminal electrodes, and

(ii) pressing said bump electrodes of said semiconductor device into said resin film so as to reach said conductive adhesive portions and contact said corresponding ones of said input/output terminal electrodes.

24. (Currently Amended) The package structure according to claim 23, further comprising:

an elastomer layer interposed between said resin layer and a functional part of said semiconductor device, said elastomer layer being softer and more elastic than said resin layer.

25. (Currently Amended) The package structure according to claim 24, wherein said resin layer comprises a said resin film or a sealing resin.

26. (Previously presented) The package structure according to claim 25, wherein said bump electrodes pass through said resin film or sealing resin.

27. (Previously presented) The package structure according to claim 24, wherein said bump electrodes pass through said resin film or sealing resin.

28. (Currently Amended) The package structure according to claim 23, wherein said resin layer comprises a said resin film or a sealing resin.

29. (Previously presented) The package structure according to claim 28, wherein said bump electrodes pass through said resin film or sealing resin.

30. (Currently Amended) The package structure according to claim 23, wherein said bump electrodes pass through said resin layer.